

CIRCUITS	DMA	DMD	DMC		
14	4.8	7.05	8.8		
16	5.6	7.85	9.6		
24	8.8	11.05	12.8		
30	11.2	13.45	15.2	⊕	
40	15.2	17.45	19.2		
50	19.2	21.45	23.2		
60	23.2	25.45	27.2		
80	31.2	33.45	35.2		

Diagram	Welding description
○	mass production & assemble mold
⊕	sample & assemble mold
⊗	mass production & fix mold
⊙	sample & fix mold

66022-XX-X-X-\*  
no. of contact

NULL-TUBE(W/O FILM)  
K: REEL(W/O FILM)  
C: REEL+FILM

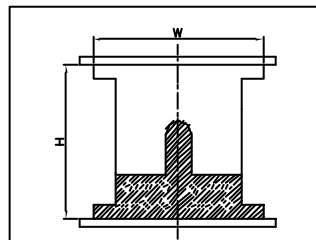
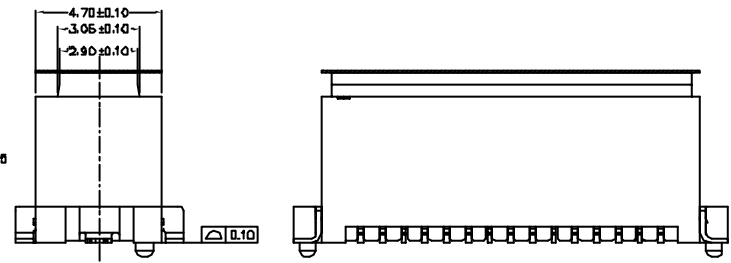
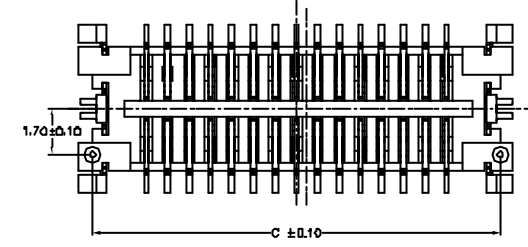
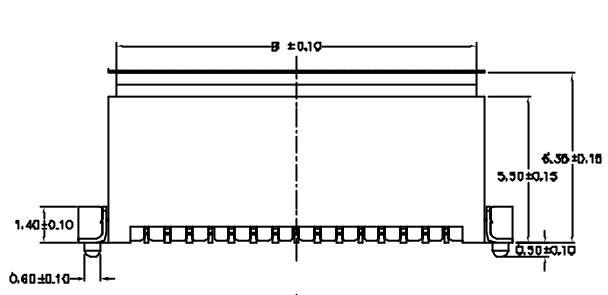
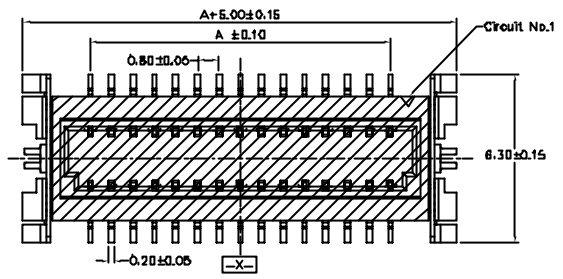
D: W/O Locating peg  
F: WITH Locating peg

Contact Plating

Definition	Code
⊕ Tin plated:	A
⊙ Gold plated:	
Flash B	15μ" F
1Dμ" E	30μ" J
⊕ Duplex plating:	
Flash K	15μ" P
1Dμ" N	30μ" U
⊕ Standard:	B

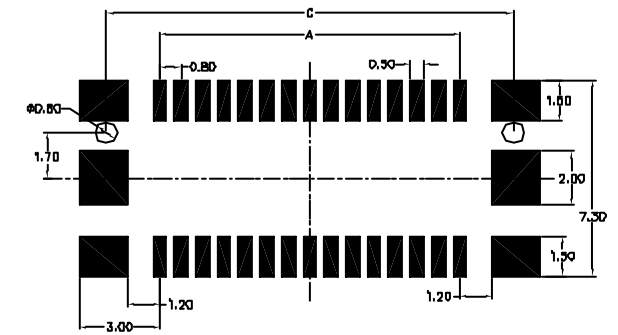
SPECIFICATIONS

Current Rating: 0.5 Amps  
 Insulator resistance: 100 Megohms Min.  
 Contact resistance: 70 m ohm Max.  
 Dielectric withstanding: AC 500 V  
 Operating Temperature: -40°C~+85°C  
 Contact Material: Phosper bronze  
 Insulator Material: High Temperature Thermoplastic, UL 94V-0  
 Color : Natural  
 Finish: Gold all over nickel



MATING DIAGRAM

66022.66029 (H=9.00mm W=6.30mm)  
 66022.66030 (H=11.00mm W=6.30mm)



RECOMMENDED P.C.B LAYOUT (TOP VIEW)  
 (PCB TOLERANCE: ±0.05)

Rev.	ECN Number	Description	Drawn	Date
2	DOC9303173	圖面新增說明	林秋蘭	04/22-04*



GENERAL TOLERANCE	
XX. ± 0.50	XXX. ±
X. ± 0.30	.XXX ±
.X ± 0.25	.X* ± 4*
.XX ± 0.20	.X* ± 4*

SCALE	1=1
UNIT	MM
SIZE	A4/X

ORIGINAL DRAWN	Bill Yang
CHECK	江坤容
APPROVE	林錫錦

DATE	04/07/04*
DATE	04/26/04*
DATE	04/26/04*

DWG. NO.	X-XX
PARTS NO.	66022-XX-X-X-*

TITLE	0.8MM BTB SOCKET
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REV.	2
SHEET	1/1